

Title (en)  
HEAT PUMP DEVICE

Title (de)  
WÄRMEPUMPENVORRICHTUNG

Title (fr)  
DISPOSITIF DE POMPE À CHALEUR

Publication  
**EP 3816535 A4 20210623 (EN)**

Application  
**EP 18923910 A 20180629**

Priority  
JP 2018024895 W 20180629

Abstract (en)  
[origin: EP3816535A1] A heat pump device according to the present invention includes: a casing, a partition wall that partitions the space in the casing into a machine chamber in which a compressor is accommodated, and an air blower chamber in which a first heat exchanger that causes heat exchange between a refrigerant and air, an air blower, and a second heat exchanger that causes heat exchange between the refrigerant and a heat medium are accommodated, and an accommodation container in which the second heat exchanger is accommodated. The accommodation container includes a first opening portion for communicating the pipe extending from the second heat exchanger with the outside from a side surface, and a protruding portion that is provided around the first opening portion and that protrudes from the side surface to the outside. The partition wall includes a second opening portion for allowing the pipe to pass therethrough. Further, the accommodation container is arranged such that the pipe passes through the second opening portion from the air blower chamber side to the machine chamber side, and the protruding portion fits into the second opening portion.

IPC 8 full level  
**F24H 4/02** (2006.01); **F24F 1/14** (2011.01); **F24F 1/30** (2011.01); **F24F 1/46** (2011.01); **F24H 9/02** (2006.01); **F24H 9/14** (2006.01); **F25B 30/02** (2006.01)

CPC (source: EP)  
**F24F 1/14** (2013.01); **F24F 1/30** (2013.01); **F24F 1/46** (2013.01); **F24H 4/02** (2013.01); **F24H 9/02** (2013.01); **F24H 9/148** (2013.01); **F25B 30/02** (2013.01); **F24F 2221/183** (2013.01); **F25B 2339/047** (2013.01)

Citation (search report)

- [XDYL] JP 2011196560 A 20111006 - PANASONIC CORP
- [Y] JP 2012145274 A 20120802 - MITSUBISHI ELECTRIC CORP
- [A] JP 2012247186 A 20121213 - PANASONIC CORP
- [A] JP 2011174643 A 20110908 - FUJITSU GENERAL LTD
- [A] EP 3296661 A1 20180321 - MITSUBISHI ELECTRIC CORP [JP]
- See references of WO 2020003511A1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 3816535 A1 20210505; EP 3816535 A4 20210623**; JP 6940000 B2 20210922; JP WO2020003511 A1 20210624; WO 2020003511 A1 20200102

DOCDB simple family (application)  
**EP 18923910 A 20180629**; JP 2018024895 W 20180629; JP 2020527142 A 20180629